CUI INC®

MODEL: HSS-B20-053H-01 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- round hole for component attachment
- solder pins for secure PCB mounting
- black anodized finish

RoHS

MODEL

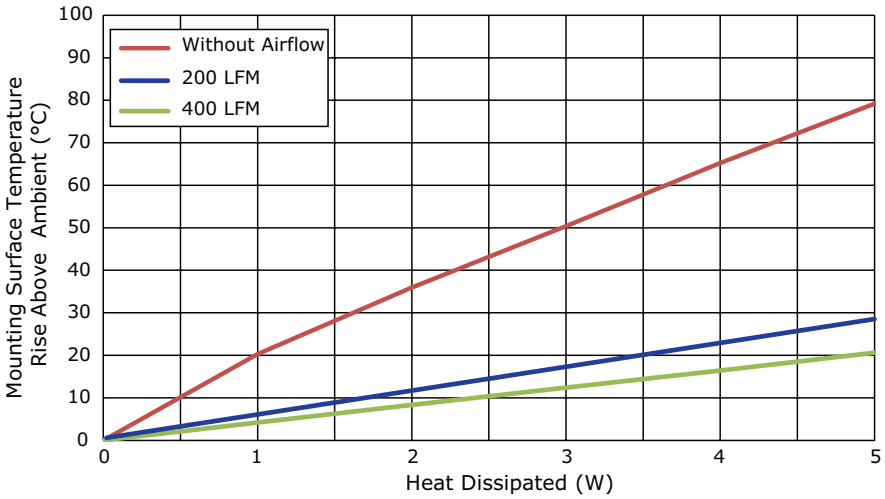
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSS-B20-053H-01	15.79	20.27	5.83	4.22	4.75

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	20.27	5.83	4.22
2	35.97	11.51	8.34
3	50.37	17.06	12.42
4	65.25	22.79	16.41
5	79.19	28.53	20.60

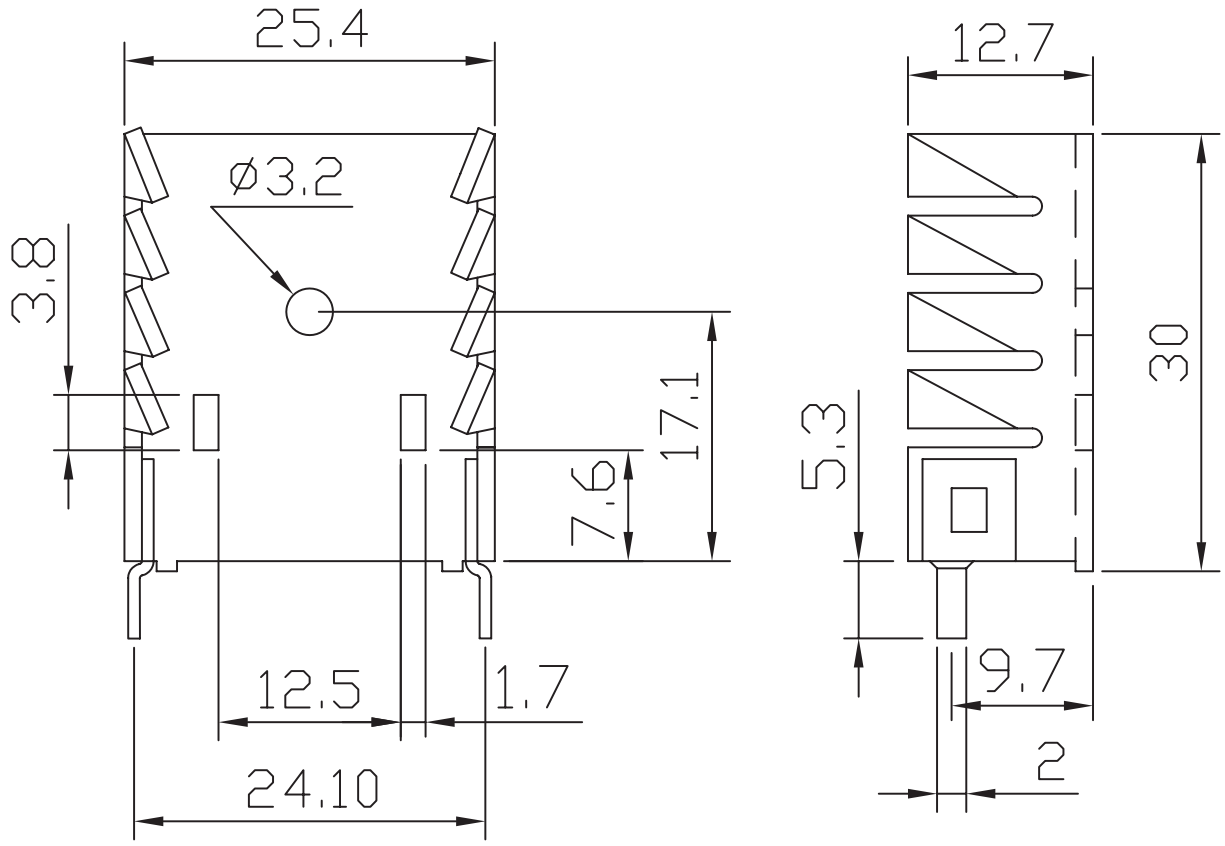
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	5.0 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/31/2017

The revision history provided is for informational purposes only and is believed to be accurate.

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